

### **Description**

The DMP3021SFVWQ-7 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

 $V_{DS} = -30V I_{D} = -50 A$ 

 $R_{DS(ON)}$  < 13m $\Omega$  @  $V_{GS}$ =-10V

### **Application**

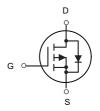
**Battery protection** 

Load switch

Uninterruptible power supply



DFN3X3-8L (Power-33-8)



P-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
DMP3021SFVWQ-7	DFN3X3-8L(Power-33-8)	HXY MOSFET	5000

## Absolute Maximum Ratings (TC=25°C unless otherwise specified)

		Rating		Units	
Symbol	Parameter	10s	Steady State	Offics	
VDS	Drain-Source Voltage	-30		V	
VGS	Gate-Source Voltage	±	±20		
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-	-50		
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-27		Α	
ID@T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-14.3	-9	Α	
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-11.4	-7.2	Α	
IDM	Pulsed Drain Current <sup>2</sup>	-130		Α	
EAS	Single Pulse Avalanche Energy³	125		mJ	
IAS	Avalanche Current	-50		А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	37		W	
Pd@Ta=25°C	Total Power Dissipation <sup>4</sup>	4.2	1.67	W	
TSTG	Storage Temperature Range	-55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150		°C	



# P-Channel Enhancement Mode MOSFET

R₀JA	Thermal Resistance Junction-Ambient <sup>1</sup>	75	°C/W
R <sub>θ</sub> JA	Thermal Resistance Junction-Ambient ¹ (t ≤10s)	30	°C/W
ReJC	Thermal Resistance Junction-Case <sup>1</sup>	3.36	°C/W

### Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

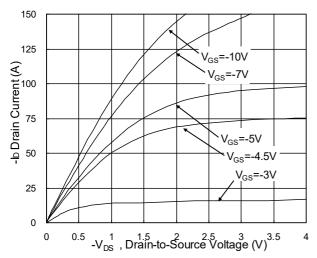
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30			V
∆BVpss/∆TJ	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.0232		V/°C
Rds(on)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-30A		9	13	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-15A		16	22	
V <sub>GS(th)</sub>	Gate Threshold Voltage		-1.2		-2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA		4.6		mV/°C
	Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			-1	- uA
loss		V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			-5	
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-30A		30		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		9		Ω
Qg	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =- 15A		22		
Qgs	Gate-Source Charge			8.7		nC
Qgd	Gate-Drain Charge			7.2		
Td(on)	Turn-On Delay Time			8		
Tr	Rise Time	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V ,		73.7		ns
Td(off)	Turn-Off Delay Time	R <sub>G</sub> =3.3Ω I <sub>D</sub> =-15A		61.8		
Tf	Fall Time			24.4		
Ciss	Input Capacitance			2215		
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		310		pF
Crss	Reverse Transfer Capacitance			237		-
ls	Continuous Source Current <sup>1,5</sup>				-42	Α
lsм	Pulsed Source Current <sup>2,5</sup>	─V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-130	Α
VsD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C			-1	V
trr	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,		19		nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C		9		nC

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us duty cycle $\leq$ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub> =-25V V<sub>GS</sub> =-10V,L=0.1mH,IAS=-50A,
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

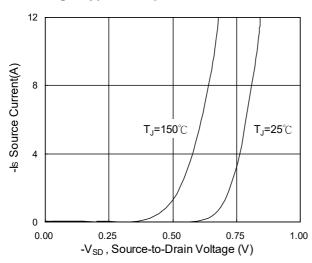


Fig.3 Forward Characteristics of Reverse

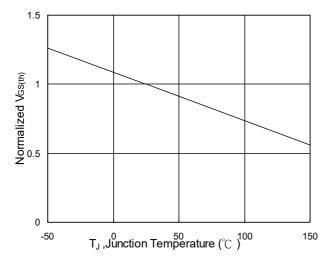


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

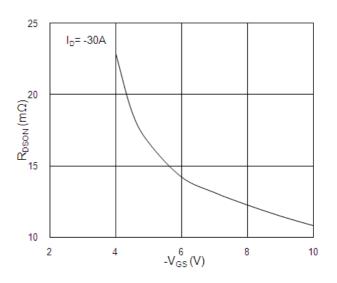


Fig.2 On-Resistance vs. G-S Voltage

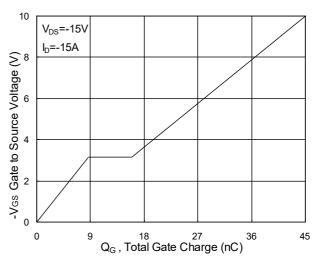


Fig.4 Gate-Charge Characteristics

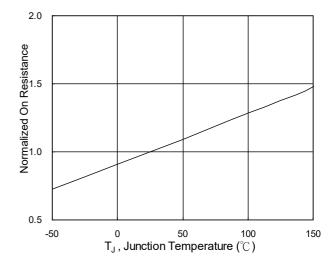
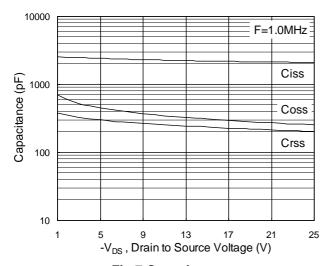


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





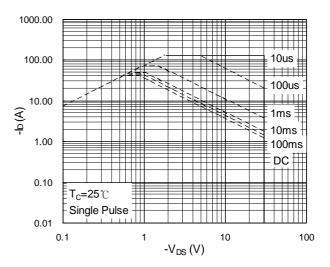


Fig.7 Capacitance

Fig.8 Safe Operating Area

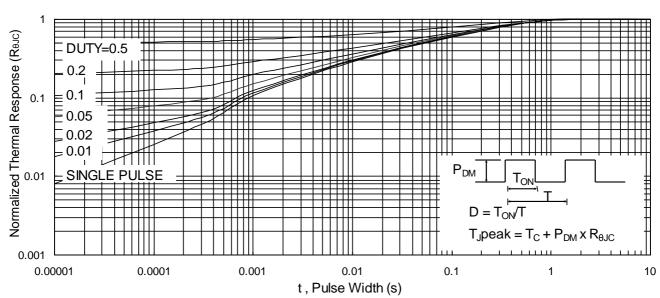


Fig.9 Normalized Maximum Transient Thermal Impedance

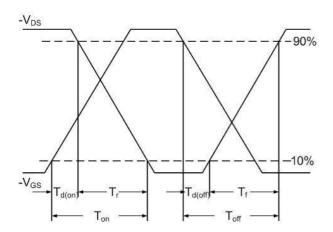


Fig.10 Switching Time Waveform

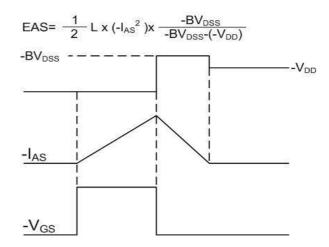
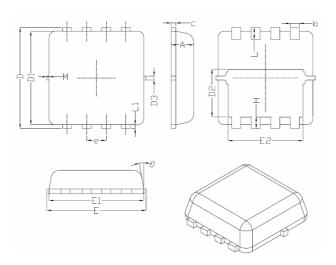


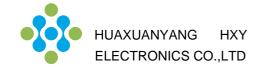
Fig.11 Unclamped Inductive Switching Waveform



## DFN3X3-8L(Power-33-8) Package Information



Sumb at	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10 <sup>°</sup>	12 <sup>°</sup>	



#### P-Channel Enhancement Mode MOSFET

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